2812

Applicant: Kie Y. Ahn et al.

Title: SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION

Docket No.:   303.672US1   Serial No.: 09/483,881
Filed: January 18, 2000   Due Date: January 19, 2005
Examiner: Ha T. Nguyen   Group Art Unit: 2812

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Mail Stop Amendment
Commissioner for Patents
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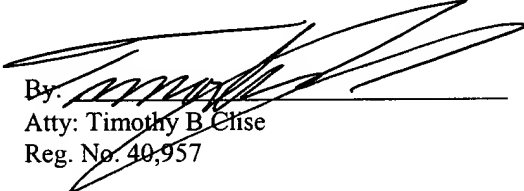
We are transmitting herewith the following attached items (as indicated with an "X"):

X   A return postcard.
X   An Amendment and Response (16 Pages).
X   A Communication Concerning Related Applications (1 pg.).
X   A Supplemental Information Disclosure Statement (2 pgs.), Form 1449 (1 pg.), and copies of 2 cited
     documents.

**If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for
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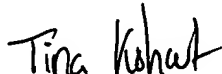Account No. 19-0743.**

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.   By: _____
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Name   Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.
                              (GENERAL)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Kie Y. Ahn et al.	Examiner: Ha T. Nguyen
Serial No.:	09/483,881	Group Art Unit: 2812
Filed:	January 18, 2000	Docket No.: 303.672US1
Title:	SELECTIVE ELECTROLESS-PLATED COPPER METALLIZATION	

AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

This responds to the Office Action dated October 19, 2004. Please amend the above-identified patent application as follows.